

through invention, technical development, publications, or new product implementation.

Prize: \$1,500 and Certificate plus one year free membership in CPMT with all CPMT Transactions.

Basis for Judging: Technical contributions through patent invention, contributions to technology or product development within the CPMT Field of Interest. May encompass management (directing) of significant new product introduction or implementation of major new electronic manufacturing processes; significantly increasing yield and/or reliability of established manufacturing processes. Contributions to the Society, through the BoG, Conferences, Chapters, etc., will also be considered. Proof of contributions may consist of open literature publications (preferred) such as papers, patents, books, and reports (available to the public). At least three (3) letters from peers and management at the nominee's place of employment attesting to the accomplishment(s) can be accepted in lieu of publications.

Eligibility: Must have been a member of the IEEE and CPMT (member grade or above) for the past three (3) years, including 2008, and must be 35 years of age, or younger, on December 31st, 2008. Please provide Date of Birth (Month/Year) to ensure eligibility.

Guidelines for Nominators:

- Minimum **three** reference letters must be submitted in support of all nominations. Reference letters can be provided by IEEE/CPMT members and non-members.
- Past recipients of an award are not eligible to receive that same award. For list of past awardees, see the CPMT Society Home page (<http://www.cpmt.org/awards>).
- An individual may submit only one nomination per award but may submit nominations for more than one award.
- It is the responsibility of the nominator to provide quality documentation to assist the Awards Committee in evaluating the candidate.
- Please send nominations to CPMT Society Awards Committee Chair by e-mail, fax or mail:

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Submitted by Eric Perfecto, Member-at-Large, CPMT Society Board of Governors

Graduates of the Last Decade (GOLD) was developed by IEEE to help young professionals transition from being a student to entering the professional world.

If you are an IEEE Member who has received your first professional degree within the last ten years, you are automatically part of IEEE GOLD!

Your CPMT society is interested in fomenting Gold member related activities – if you would like to like to be part of the CPMT Gold group please contact CPMT Board of Governors member Eric Perfecto (perfecto@us.ibm.com).

Conference News:

CONFERENCES IN 2009:

2009 11th Electronics Packaging Technology Conference (EPTC 2009)

9-11 December 2009, Singapore
<http://www.eptc-ieee.net/>

2009 IEEE Electrical Design of Advanced Packaging & Systems Symposium (EDAPS 2009)

December 2-4, 2009 Hong Kong, China
<http://www.edaps2009.org/>
Contact: edaps2009@ee.cuhk.edu.hk

CONFERENCES IN 2010:

2010 60th Electronic Components and Technology Conference (ECTC 2010)

June 1 - 4, 2010 Las Vegas, NV, USA
<http://www.ectc.net>
Contact: Jean Trewhella, jeanmh@us.ibm.com

3rd Electronics Systemintegration Technology Conference (ESTC 2010)

September 13-16, 2010 Berlin, Germany
http://www.estc.biz/outlook_estc_2010/ Contact: Rolf Aschenbrenner, rolf.aschenbrenner@izm.fraunhofer.de

See the CPMT Society website for updates:

www.cpmt.org/conf

3rd Electronic System-Integration Technology Conference (ESTC) to take place in Berlin from September 13-16, 2010

Submitted by Rolf Aschebrener, VP Conferences, CPMT Society

There are three IEEE CPMT flagship conferences worldwide: the annual conference ECTC located in the USA, the EPTC which takes place once a year in Singapore and the biennial European

conference Electronics System-Integration Technology Conference (ESTC).

After its two very successful predecessor events in Dresden (2006) with the General Chair Klaus-Jürgen Wolter from the Technical University Dresden and in Greenwich (2008), where Prof. Chris Bailey from the University of Greenwich was the General Chair of the conference, the 3rd ESTC in September 2010 in Berlin will again feature a powerful technical program, as well as professional short courses on modern technologies. The ESTC 2010's General Chair will be Rolf Aschenbrenner from the Fraunhofer IZM in Berlin.

The ESTC 2010 is a global event brings together key researchers, innovators, decision-makers, technologists, businesses, and standards bodies working in microelectronic packaging. Organized by IEEE-CPMT since 2006, the conference series is the premier venue for academics and industry to present, demonstrate, and discuss the latest developments in assembly and interconnection technology and new innovative applications.

The concurrent exhibition will facilitate the presentation of state-of-the-art technological services and equipment to an interested audience of international decision-makers from science and industry.

ESTC 2010 seeks original papers describing research in all areas of electronic packaging. Papers may be submitted to the following tracks:

- Advanced packaging
- Microsystem packaging
- New materials and processes
- Optoelectronics
- Assembly and manufacturing technology
- Modelling and simulation
- Applied Reliability
- Power electronics
- Electrical design and modelling
- Emerging technologies

Abstract submission deadline is **February 1, 2010**. For more detailed information please go to www.estc-2010.de

Contact: Rolf Aschenbrenner, Fraunhofer IZM - rolf.aschenbrenner@izm.fraunhofer.de

15th International Symposium for Design and Technology of Electronics Packages – SIITME 2009

Submitted by Réka Bátorfi, IEEE CPMT Hu&Ro Joint Chapter

Between the 17th and 20th of September, 2009, the 15th International Symposium for Design and Technology of Electronics Packages (SIITME) was arranged for the first time outside Romania, in the beautiful spa town, Gyula, Hungary. This conference is an annual event in Central and Eastern Europe since 1995, having a special interest to improve and to implement new electronics technologies. The topics cover design, simulation and quality aspects of electronics packages,

devices and circuit modules. There were also a biomedical and an educational topic, the latter is a perspective field, as e-learning and life-long learning are becoming more and more important in these new member states of the European Union.

The Symposium is traditionally a forum of scientists and researchers both from academia and the industry. This year the professors, young scientists and students were from Germany, Poland, Slovenia, Czech Republic, Slovakia, Romania and Hungary. The Romanian participants came from all over the country, representing the technical universities from Bucharest, Cluj-Napoca, Pitesti, Suceava, Timisoara, Galati, Alba Iulia, Iasi, and Brasov. The SIITME is especially popular among Ph.D. students and young researchers, more than 60 % of the participants being from this group. Every year it is a very good opportunity for them to share their scientific ideas, and present their research work at an international forum.

SIITME has always been strongly supported by CETTI of Politehnica University of Bucharest, the IEEE-CPMT Hu&Ro Joint Chapter and ARIES (Romanian Association for Electronic and Software Industry). This year, the activities of the Joint Chapter were the organization of the whole conference, both in scientific and in technical way, which has lead to a high level conference and a friendly and enjoyable atmosphere. Not just the local organizers, but also the members from Romania contributed with a lot of work to have a successful event.

The SIITME 2009 also was an IEEE Conference, registered in the conference database. After the final evaluation, the papers of the highest scientific value are included in the IEEE Xplore webpage. The members of the steering and the scientific committees have done a hard work helping the authors and evaluating their abstracts, papers and presentations.



The opening ceremony of the 15th SIITME in the Town Hall of Gyula (from left to right: Árpád Szabó, Ioan Fodoreanu, Paul Svasta, Zsolt Illyefalvi-Vitéz, Dan Pitica)

The Town council was represented by Dr. Klára Perjési, the Mayoress of Gyula and Mr. Árpád Szabó, the Deputy Mayor of Gyula. It was also our honour that Mr. Ioan Fodoreanu, the General Consul of Romania in Hungary also participated in the Opening session and had the opportunity to meet Prof. Paul Svasta General Chair of SIITME, Prof. Zsolt Illyefalvi-Vitéz Conference Chair of SIITME2009 and Prof. Dan Pitica Chair of the IEEE-CPMT Hu&Ro Joint Chapter.

Demonstrating the traditionally good and fruitful relationship among the member countries, a workshop about a common EU project, Elect2eat (www.elect2eat.eu) was organized during the Symposium. This project initiates life-long e-learning in electronics design and technology, improving the knowledge of students in vocational education schools and of skilled workers in electronics assembling companies. There is also a scientific bilateral cooperation between Romania and Hungary, with the topic of low-energy consuming joining technologies. Several papers were written in the frame of this cooperation at this and other previous international conferences (ISSE, IMAPS Cz&Sk). At SIITME 2009, Radu Bunea presented a paper about laser soldering topic, which is the result of his 6-week stay in Hungary, where he did experiments with the help of the local experts.

were given to Ms. Marina Santo Zarnik (HIPOT Slovenia) and to Mr. Radu Arsinte (TU Cluj-Napoca). Acknowledgements were expressed to Ms. Georgiana Buta (Stefan cel Mare University, Suceava), Mr. Iulian Busu (UPB-CETTI, Bucharest) and to Mr. Mihai Machedon (TU Brasov).

During the whole conference, the organizers made efforts to present Hungary and to have an overview of the local specialties. One of them was a *pálinka* tasting and the secrets of the production were also shown. The participants had the opportunity to visit the castle and the spa. These occasions enhanced the contacts and networking which forecast future scientific and social relationships.

Chapter News:

Report by IEEE Singapore REL/CPMT/ED Chapter for July-Sep 2009

Submitted by Kin-Leong PEY, Chair - Singapore REL/CPMT/ED Chapter

Together with Institute of Microelectronics, the Chapter jointly organized a talk on 20 July 2009 on "Recent Advances in Anisotropic Conductive Adhesives (ACAs) Interconnection Technology – Low Temperature and Fast Assembly Methods" by Prof Kyung-Wook Paik, Korea Advanced Institute of Science and Technology (KAIST). He response was overwhelmed with about 80 participants attended this talk.

Jointly organized with the Microelectronic Center, School of Electrical and Electronic Engineering, Nanyang Technological University, the Chapter organized a Workshop and IEEE EDS Mini-colloquium on NANometer CMOS Technology (called 20th WIMNACT) on 11 August 2009. Three EDS Distinguished Lecturers (Prof. Juzer Vasi, IIT Bombay, India, Prof. Ramgopal Rao, IIT Bombay, India and Dr. Samar Saha (IEEE EDS VP Publications), Silterra USA Inc., USA) presented three talks. The workshop was officially opened by Prof. Kam Chan Hin, Chair of the School of Electrical and Electronic Engineer, NTU. These were Modeling and Simulation of Flash Memory Devices by Prof. Vasi, Polymer Based Sensor Systems for Healthcare & Homeland Security by Prof. Rao and Device Considerations for Ultra-Low Voltage Analog Integrated Circuits by Dr. Saha. About 30 participants attended the talk.

The Chapter co-hosted the 16th IEEE International Symposium on the Physical and Failure Analysis of Integrated Circuits (IPFA 2009). It was held from 6-10th July 2009 in Suzhou, China. Eight tutorials were conducted on 6 and 7 July 2009, with two parallel sessions. 15 invited papers were presented over the 3-day symposium from 8 to 10 July 2009. This is the first time that IPFA is being held in China and despite the global financial crisis, almost 200 abstracts were received. For the 3-day symposium, there were two parallel sessions with 81 oral presentations. A record 94 papers were accepted for the poster presentations. There were more than 200 participants for the tutorials and symposium and 27 exhibitors participated. The "Art of Failure Analysis" Photo Contest attracted some high quality photographs. The first-prize photo was featured on the cover page of the IEEE Spectrum online and the top 10 entrants were included as a slideshow in the IEEE Spectrum



The awarding ceremony of SIITME 2009, for Best and Excellent Poster Awards

At the closing ceremony, the best scientists were awarded: the Best Poster Award was given to Mr. Ciprian Ionescu (UPB-CETTI, Bucharest) for the paper entitled Electrochemical Sensor with Polymer Thick Film Printed Electrodes; the Best Poster Award for Young Scientist was given to Mr. Rajmond Jánó (TU Cluj-Napoca), for the paper entitled Intelligent Human Interface Device. Excellent Poster Awards for Young Scientist were given to Mr. Cosmin Tamas (UPB-CETTI, Bucharest), Mr. Olivér Krammer (BME-ETT, Budapest), Mr. Constantin Barabasa (Gh. Asachi TU, Iasi) and Mr. Radu Bunea (UPB-CETTI, Bucharest). Excellent Poster Awards



Cornell University



IEEE COMPONENTS, PACKAGING AND
MANUFACTURING TECHNOLOGY SOCIETY

Flexible Electronics Symposium

The second annual **Flexible Electronics Symposium**, hosted by Binghamton University's Center for Advanced Microelectronics Manufacturing, (CAMM), in conjunction with the IEEE Components, Packaging and Manufacturing Technology Society, Sandia National Laboratories and Cornell University, was held on August 19, 2009 in Binghamton, New York.

This workshop brought together over 120 leading researchers from academia, national labs, government and industry with the goal of developing collaborative partnerships on emerging flexible electronic technologies that will impact energy, environment, military and homeland security applications. Presentations were given in the fields of flexible electronics, functional printing, and emerging electronic materials. The workshop provided the opportunity for participants to review and share new research findings in critical technology areas and identify issues for the rapidly growing flexible electronics field. As part of the workshop, attendees toured the Center for Advanced Microelectronics Manufacturing (CAMM), a national research lab focusing on roll-to-roll flexible electronics, and a networking dinner.

Speakers included: Bahgat Sammakia and James Turner, Binghamton University; David Gundlach, National Institutes for Standards and Technology; Changsoo Jang, University of Maryland, College Park; Dahwey Chu, Sandia National Laboratory; Kelly Lee and RJ Greco, Infotonics Technology Center; Christopher Ober, Cornell University; Charles Becker and Jeff Ash, General Electric; Minqian He, Corning Incorporated; and Fazila Seker, Xerox Research Center of Canada.

The workshop was held in conjunction with the Flex Tech Alliance's quarterly working group on Flexible, Printed and Organic Electronics.

The next symposium is scheduled for June, 2010.

Access Papers from Recent CPMT Conferences

You read, in the President's message (page 3), that he finds that conference papers are the critical links in our global knowledge supply chain. In CPMT-sponsored conferences, one regularly finds ideas for new innovations and interesting research results. Are you taking advantage of this "knowledge supply chain" to replenish your technical knowledge and discover where the technology is going? Here's your chance.

Here are the links to Proceedings and papers from the summer and fall CPMT Society conferences. Most researchers belong to companies or institutions that subscribe to the full IEEE collection. If your work/university domain isn't automatically recognized by your browser, please contact your librarian.

Electronic Components and Technology Conf, ECTC 2009.
59th - ieeexplore.ieee.org/servlet/opac?punumber=5066986

European Microelectronics and Packaging Conference, EMPC 2009. - ieeexplore.ieee.org/servlet/opac?punumber=5238690

Int'l Conf on Electronic Packaging Technology & High Density Packaging, 2009. ICEPT-HDP -
ieeexplore.ieee.org/servlet/opac?punumber=5234372

Signal Propagation on Interconnects, 2009. SPI. IEEE Workshop on - ieeexplore.ieee.org/servlet/opac?punumber=5073942

31st Int'l Spring Seminar on Electronics Technology, 2008. ISSE - ieeexplore.ieee.org/servlet/opac?punumber=5254892

55th IEEE Holm Conf on Electrical Contacts, 2009
- ieeexplore.ieee.org/servlet/opac?punumber=5284378

IEEE Int'l Conf on 3D System Integration, 2009. 3DIC
- ieeexplore.ieee.org/servlet/opac?punumber=5290624

Second Int'l Conf on Thermal Issues in Emerging Technologies, 2008. ThETA ieeexplore.ieee.org/servlet/opac?punumber=5159257

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